1 Form A APY215G1E_EH APSEMI SMD-4/DIP-4 Load Voltage:150V Load Current:1.1A TSCA Parameter Symbol Units Rating E534710 Load Voltage VL V 150 Load Current А ΙL 1.1 0.45 On-Resistance Ron Ω I/O Breakdown Voltage 5000 Vrms V/io (+) Input 1 \cap $\sqrt{2}$ E1 IF (AC.DC) (-) 1 I FD Anode

APSEMI PhotoRelays

R

APSEMI Photorelays are the most reliable, technically advanced logic-to-power interface devices. Their basic function is to take a low current signal from a microprocessor to control the switching of both AC and DC loads, while providing an isolation barrier between logic and power. While this function is common to all relays, Photorelays provide distinct advantages over their mechanical counterparts including:

LED Cathode
3.4. Drain(MOS FET)

• Long life (No limit on mechanical and electrical

AC/DC

- lifetime)Bounce-free switching
- Higher speed and high frequency switching
- Higher sensitivity (less power consumption)
- Immunity to EMI or RFI

- No have voltaic arc, bounce, and noise More
- resistant to vibration and impact AC or DC load

SMD-4

DIP-4

- switching
 - Small package size

Function

APSEMI PhotoRelays operate by taking a low level input current (<5mA) that energizes an input Infrared LED, which is optically-coupled to a Photo-diode array chip. This IC in turn generates a photo voltage that powers two MOSFETs typically connected in a source-to-source con! guration, allowing for both AC and DC output loads. Photorelay basically move photons to accomplish their switching function, they incur no mechanical wear and tear, providing consistent reliable switching.

Applications

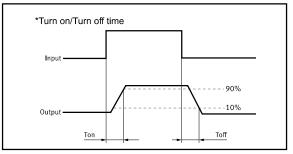
These advantages make APSEI Photorelays the ideal choice for:

- Telecom/Datacom switching
- Multiplexers
- Meter reading systems
- Data acquisition
- Medical equipment
- Battery monitoring
- I/O Sub-Systems

- Robotics Aerospace
- Home/Safety security systems
- Process Control
- Energy Management
- Reed Relay EMR Replacement
- Programmable Controllers

TPYES

Category	Output Rating		Baakaga	Part No.	Pool/ing Quantity	
	Load Voltage	Load Current	Package	Fall NO.	Packing Quantity	
AC/DC	150V	1.1A	DIP-4	APY215G1E	50pcs /tube	
			SMD-4	APY215G1EH	1000pcs /reel	



Absolute Maximum Ratings (Ta = 25°C)

Item		Symbol	Value	Units	Note	
	Continuous LED Current	IF	50	mA		
Input	Peak LED Current	I FP	1000	mA	f=100Hz, duty=1%	
	LED Reverse Voltage	VR	5	V		
	Input Power Dissipation	Pin	75	mW		
	Load Voltage	VL	150	V(AC peak or DC)		
	Load Current	L	1.1	А		
Output	Peak Load Current	Peak	2.8	А	100ms(1 pulse)	
	Output Power Dissipation	Pout	350	mW		
Total Power Dissipation		Ρτ	400	mW		
I/O Breakdown Voltage		Vi/o	5000	Vrms	RH=60%, 1min	
Operating Temperature		Topr	-40 to 85	°C		
Storage Temperature		Tstg	-40 to 100	°C		
Pin Soldering Temperature		Tsol	260	°C	10 sec max.	

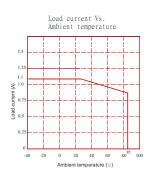
Electrical Characteristics (Ta = 25°C)

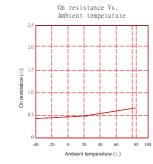
	Item	Symbol	MIN.	TYP.	MAX.	Units	Conditions
	LED Forward Voltage	VF		1.2	1.4	V	l⊧=10mA
Input	Operation LED Current	Fon		1.5	5.0	mA	
	Recovery LED Current	Foff		0.35	0.5	mA	
	Recovery LED Voltage	VFoff	0.5			V	
							l⊧=5mA,I∟=100mA,
Output	On-Resistance	Ron		0.45	0.7	Ω	Time to flow is within 1 sec.
	Off-State Leakage	Leak	0.01	0.03	0.10	uA	V₋=Rating
	Current	Leak	0.01	0.03	0.10	uA	
	Output Capacitance	Cout		90		pF	V∟=0, f=1MHz
Transmis	Turn-On Time	Ton		1.5	5.0	ms	l⊧=5mA, l∟=100mA,
sion	Turn-Off Time	Toff		0.08	2.0	ms	
Coupled	I/O Isolation Resistance	Ri⁄o	10 ¹⁰			Ω	DC500V
	I/O Capacitance	Ci/o		0.8	1.5	pF	f=1MHz

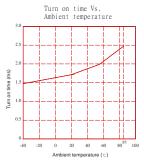
Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value): IF ≥5mA and ≤30mA

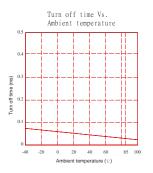
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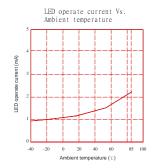
Engineering Data

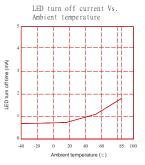








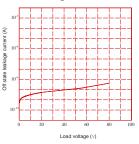


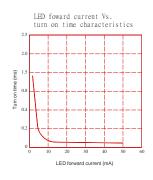


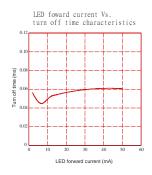
LED forward voltage Vs. Ambient temperature Voltage Vs. currennt characteristics of output at MOS portion $% \left({{\left[{{{\rm{NOS}}} \right]} \right]_{\rm{COS}}} \right)$

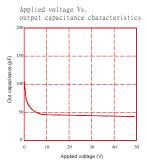
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		Voltage, V-
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		0-+

Off state leakage current Vs. Load voltage characteristics







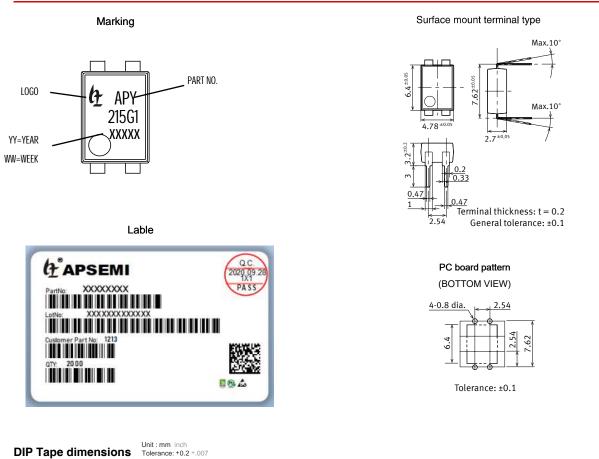


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Dimensions and DIP-4 Package Unit: mm

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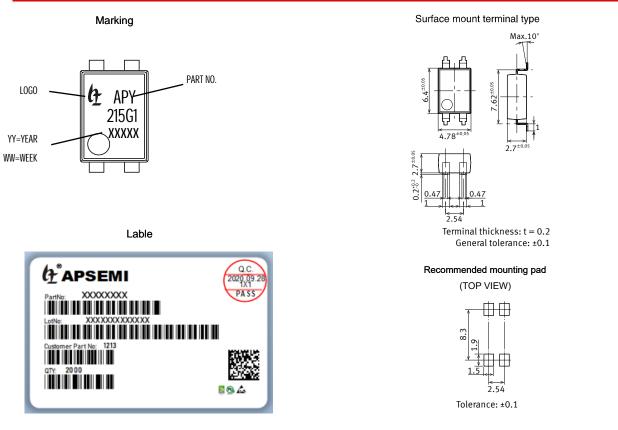
Devices are packaged in a tube so that pin No. 1 is on the stopper B side. Observe correct orientation when mounting them on PC boards.



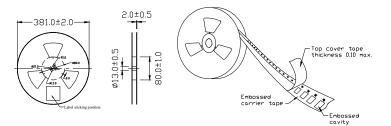
Dimensions and SMD-4 Package Unit: mm

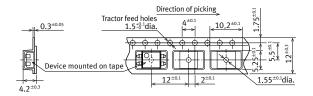
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Tape dimensions (tape reel)



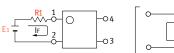


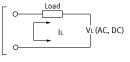
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Using Methods

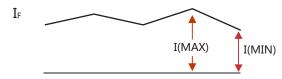
Examples of resistance value to control LED forward current (IF=5mA)





E1	R1 (Approx)			
3.3V	300 Ω			
5.0V	600 Ω			
12V	1.9KΩ			
24V	4.1K Ω			

LED forward current must be more than 5mA , at I(MIN) ,and less than 30mA , at I(MAX).



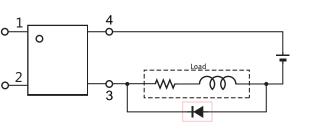
Recommended Operating Conditions

Please obey the following conditions to ensure proper device operation and resetting. Input LED current (Recommended value):

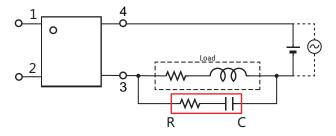
Characteristic	Symbol	Min	Тур.	Max	Unit
Forward current	١ _F	5.0	7.0	30	mA

Protection Circuit

Clamp diode is connected in parallel with the load. Absorb capacity with external diode.



CR Snubber is connected in parallel with the load. Absorb capacity with buffer capacity.



When adding diodes, buffer circuits (C-R), and other protections, they need to be installed near the MOS RELAY to be effective. Adding protection elements may result in a slow reset time, so adjust them according to the actual situation before use.

Note: When developing designs using this product, perform the expected performance of the equipment under the operating conditions recommended by the guidelines in this document. Continuous use under heavy loads (including, but not limited to, the application of high temperatures/current/voltage and significant changes in temperature, etc.) may result in deterioration of the reliability of this product.

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